# 505139633 10/12/2018

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

#### **CONVEYING PARTY DATA**

Name	Execution Date
TIN TIN WEE	08/20/2017
TRILOCHAN SAHOO	08/28/2017
SUNIL SUKUMARAPILLAI	08/28/2017
ARUN KUMAR KODIGENAHALLI VENKATESWAR	08/28/2018

### **RECEIVING PARTY DATA**

Name:	QUALCOMM INCORPORATED	
Street Address:	5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	16159042	

## **CORRESPONDENCE DATA**

**Fax Number:** (801)413-0106

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** (949) 681-8161

Email:qualcomm-pto@lozaip.comCorrespondent Name:LOZA & LOZA, LLP/QUALCOMMAddress Line 1:305 N. SECOND AVE., #127Address Line 4:UPLAND, CALIFORNIA 91786

ATTORNEY DOCKET NUMBER: QCOM-3576D1 (174624D1)

NAME OF SUBMITTER: EUGENE WORLEY

SIGNATURE: /Eugene Worley/

DATE SIGNED: 10/12/2018

**Total Attachments: 4** 

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### ASSIGNMENT

### WHEREAS, WE,

- 1. Tin Tin WEE, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
- 2. Trilochan SAHOO, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of Bangalore, India,
- 3. Sunil SUKUMARAPILLAI, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of Bangalore, India,
- 4. Arun Kumar Kodigenahalli VENKATESWAR, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of Bangalore, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to LAYOUT TECHNIQUE FOR MIDDLE-END-OF-LINE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/628,909 filed June 21, 2017, Qualcomm Reference No. 174624, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world

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in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ···	Tan Dirego, C	4. on 8	1/20/2017	Tin Tin WEE
	LOCATION	······································	DATE	Tin Tin WEE
Done at _	LOCATION	_, on		
	LOCATION		DATE	Trilochan SAHOO
Done at		_, on		Sunil SUKUMARAPILLAI
	LOCATION		DATE	Sunil SUKUMARAPILLAI
Done at		on_		Arun Kumar Kodigenahalli VENKATESWAR
-	LOCATION		DATE	Arun Kumar Kodigenahalli VENKATESWAR

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	LOCATION ,	on	Tin Tin WEE
Done at	Bongalow, LOCATION	on <u>28 th day 201</u> 7 DATE	Trilochan SAHOO
Done at	Bangalen /w/ LOCATION	)/A on <u>~28<sup>7‡</sup> Abt. 28/</u> 7 DATE	Sunil SUKUMARAPILLAI
Ĵ∂./ Done at	golore, India	on <u>28 Ava joiz</u> DATE	Arun Kumar Kodigenahalli VENKATESWAR

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**RECORDED: 10/12/2018**